

WAFER PROCESSING METHOD

ABSTRACT OF THE DISCLOSURE

A wafer processing method includes a polyolefin
5 sheet providing step of positioning a wafer in an inside
opening of a ring frame and providing a polyolefin sheet
on a back side of the wafer and on a back side of the
ring frame, a uniting step of heating the polyolefin
sheet as applying a pressure to the polyolefin sheet to
10 thereby unite the wafer and the ring frame through the
polyolefin sheet by thermocompression bonding, a dividing
step of cutting the wafer by using a cutting apparatus to
thereby divide the wafer into individual device chips,
and a pickup step of heating the polyolefin sheet,
15 pushing up each device chip through the polyolefin sheet,
and then picking up each device chip from the polyolefin
sheet.

FIGURE 4